

**SN74SSTV32852**  
**24-BIT TO 48-BIT REGISTERED BUFFER**  
**WITH SSTL\_2 INPUTS AND OUTPUTS**

SCES361C – AUGUST 2001 – REVISED FEBRUARY 2003

- Member of the Texas Instruments Widebus™ Family
- 1-to-2 Outputs Support Stacked DDR DIMMs
- Supports SSTL\_2 Data Inputs
- Outputs Meet SSTL\_2 Class II Specifications
- Differential Clock (CLK and  $\overline{\text{CLK}}$ ) Inputs
- Supports LVCMOS Switching Levels on the  $\overline{\text{RESET}}$  Input
- $\overline{\text{RESET}}$  Input Disables Differential Input Receivers, Resets All Registers, and Forces All Outputs Low
- Pinout Optimizes DIMM PCB Layout
- One Device Per DIMM Required
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 1000-V Charged-Device Model (C101)

**description/ordering information**

This 24-bit to 48-bit registered buffer is designed for 2.3-V to 2.7-V  $V_{CC}$  operation.

All inputs are SSTL\_2, except the LVCMOS reset ( $\overline{\text{RESET}}$ ) input. All outputs are SSTL\_2, Class II compatible.

The SN74SSTV32852 operates from a differential clock (CLK and  $\overline{\text{CLK}}$ ). Data are registered at the crossing of CLK going high and  $\overline{\text{CLK}}$  going low.

The device supports low-power standby operation. When  $\overline{\text{RESET}}$  is low, the differential input receivers are disabled, and undriven (floating) data, clock, and reference voltage ( $V_{REF}$ ) inputs are allowed. In addition, when  $\overline{\text{RESET}}$  is low, all registers are reset and all outputs are forced low. The LVCMOS  $\overline{\text{RESET}}$  input always must be held at a valid logic high or low level.

To ensure defined outputs from the register before a stable clock has been supplied,  $\overline{\text{RESET}}$  must be held in the low state during power up.

**ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	LFBGA – GKF	Tape and reel	SN74SSTV32852GKFR	SV852

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



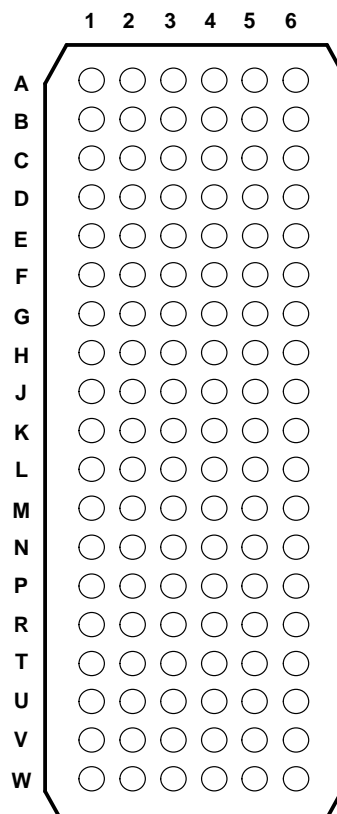
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**GKF PACKAGE**  
**(TOP VIEW)**



**terminal assignments**

	1	2	3	4	5	6
A	Q2A	Q1A	CLK	$\overline{\text{CLK}}$	Q1B	Q2B
B	Q3A	V <sub>DDQ</sub>	GND	GND	V <sub>DDQ</sub>	Q3B
C	Q5A	Q4A	V <sub>DDQ</sub>	V <sub>DDQ</sub>	Q4B	Q5B
D	Q7A	Q6A	GND	GND	Q6B	Q7B
E	Q8A	GND	V <sub>DDQ</sub>	V <sub>DDQ</sub>	GND	Q8B
F	Q10A	Q9A	V <sub>DDQ</sub>	V <sub>DDQ</sub>	Q9B	Q10B
G	Q12A	Q11A	GND	GND	Q11B	Q12B
H	Q13A	V <sub>CC</sub>	V <sub>DDQ</sub>	V <sub>DDQ</sub>	V <sub>CC</sub>	Q13B
J	Q14A	Q15A	GND	GND	Q15B	Q14B
K	Q17A	Q16A	V <sub>DDQ</sub>	V <sub>DDQ</sub>	Q16B	Q17B
L	Q18A	Q19A	GND	GND	Q19B	Q18B
M	Q20A	V <sub>DDQ</sub>	GND	GND	V <sub>DDQ</sub>	Q20B
N	Q22A	Q21A	V <sub>DDQ</sub>	V <sub>DDQ</sub>	Q21B	Q22B
P	Q23A	V <sub>DDQ</sub>	GND	GND	V <sub>DDQ</sub>	Q23B
R	Q24A	V <sub>CC</sub>	$\overline{\text{RESET}}$	V <sub>REF</sub>	V <sub>CC</sub>	Q24B
T	D2	D1	D6	D18	D13	D14
U	D4	D3	D10	D22	D15	D16
V	D5	D7	D11	D23	D19	D17
W	D8	D9	D12	D24	D21	D20

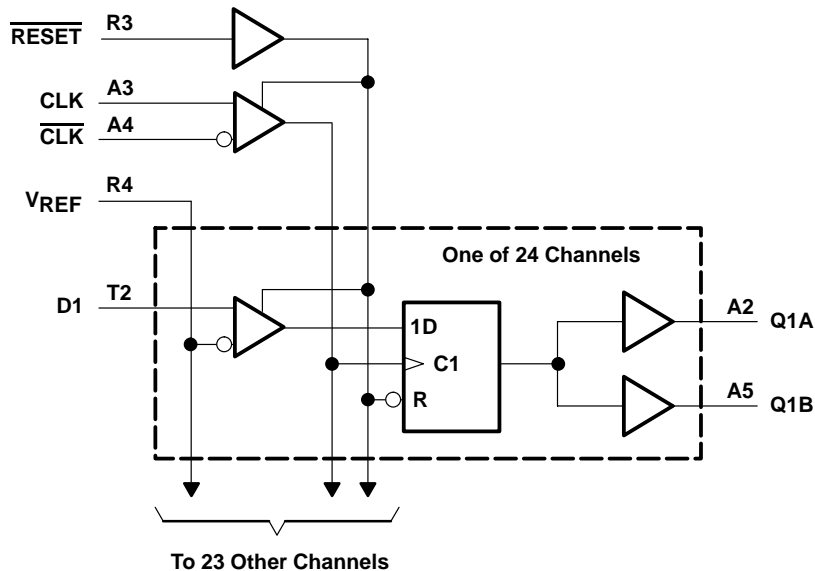
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**FUNCTION TABLE**

INPUTS				OUTPUT
RESET	CLK	CLK	D	Q
H	↑	↓	H	H
H	↑	↓	L	L
H	L or H	L or H	X	Q <sub>0</sub>
L	X or floating	X or floating	X or floating	L

**logic diagram (positive logic)**



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$ or $V_{DDQ}$ .....	–0.5 V to 3.6 V
Input voltage range, $V_I$ (see Notes 1 and 2) .....	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, $V_O$ (see Notes 1 and 2) .....	–0.5 V to $V_{DDQ} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	–50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{DDQ}$ ) .....	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{DDQ}$ ) .....	±50 mA
Continuous current through each $V_{CC}$ , $V_{DDQ}$ , or GND .....	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3) .....	36°C/W
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
 2. This value is limited to 3.6 V maximum.  
 3. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN74SSTV32852

## 24-BIT TO 48-BIT REGISTERED BUFFER

### WITH SSTL\_2 INPUTS AND OUTPUTS

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#### recommended operating conditions (see Note 4)

		MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage	V <sub>DDQ</sub>		2.7	V
V <sub>DDQ</sub>	Output supply voltage	2.3		2.7	V
V <sub>REF</sub>	Reference voltage (V <sub>REF</sub> = V <sub>DDQ</sub> /2)	1.15	1.25	1.35	V
V <sub>TT</sub>	Termination voltage	V <sub>REF</sub> -40mV	V <sub>REF</sub>	V <sub>REF</sub> +40mV	V
V <sub>I</sub>	Input voltage	0		V <sub>CC</sub>	V
V <sub>IH</sub>	AC high-level input voltage	Data inputs	V <sub>REF</sub> +310mV		V
V <sub>IL</sub>	AC low-level input voltage	Data inputs		V <sub>REF</sub> -310mV	V
V <sub>IH</sub>	DC high-level input voltage	Data inputs	V <sub>REF</sub> +150mV		V
V <sub>IL</sub>	DC low-level input voltage	Data inputs		V <sub>REF</sub> -150mV	V
V <sub>IH</sub>	High-level input voltage	$\overline{\text{RESET}}$	1.7		V
V <sub>IL</sub>	Low-level input voltage	$\overline{\text{RESET}}$		0.7	V
V <sub>ICR</sub>	Common-mode input voltage range	CLK, $\overline{\text{CLK}}$	0.97	1.53	V
V <sub>I(PP)</sub>	Peak-to-peak input voltage	CLK, $\overline{\text{CLK}}$	360		mV
I <sub>OH</sub>	High-level output current			-20	mA
I <sub>OL</sub>	Low-level output current			20	
T <sub>A</sub>	Operating free-air temperature		0	70	°C

NOTE 4: The  $\overline{\text{RESET}}$  input of the device must be held at valid logic voltage levels (not floating) to ensure proper device operation. The differential inputs must not be floating unless RESET is low. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP†	MAX	UNIT				
V <sub>IK</sub>		I <sub>I</sub> = -18 mA	2.3 V			-1.2	V				
V <sub>OH</sub>		I <sub>OH</sub> = -100 μA	2.3 V to 2.7 V	V <sub>DDQ</sub> -0.2			V				
		I <sub>OH</sub> = -16 mA	2.3 V	1.95							
V <sub>OL</sub>		I <sub>OL</sub> = 100 μA	2.3 V to 2.7 V			0.2	V				
		I <sub>OL</sub> = 16 mA	2.3 V			0.35					
I <sub>I</sub>	All inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	2.7 V			±5	μA				
I <sub>CC</sub>	Static standby	$\overline{\text{RESET}}$ = GND	2.7 V			10	μA				
	Static operating	$\overline{\text{RESET}}$ = V <sub>CC</sub> , V <sub>I</sub> = V <sub>IH(AC)</sub> or V <sub>IL(AC)</sub>						I <sub>O</sub> = 0	35	mA	
I <sub>CCD</sub>	Dynamic operating – clock only	$\overline{\text{RESET}}$ = V <sub>CC</sub> , V <sub>I</sub> = V <sub>IH(AC)</sub> or V <sub>IL(AC)</sub> , CLK and $\overline{\text{CLK}}$ switching 50% duty cycle	2.7 V			46	μA/MHz				
	Dynamic operating – per each data input	$\overline{\text{RESET}}$ = V <sub>CC</sub> , V <sub>I</sub> = V <sub>IH(AC)</sub> or V <sub>IL(AC)</sub> , CLK and $\overline{\text{CLK}}$ switching 50% duty cycle, One data input switching at one-half clock frequency, 50% duty cycle						I <sub>O</sub> = 0	12	μA/clock MHz/D input	
r <sub>OH</sub>	Output high	I <sub>OH</sub> = -20 mA	2.3 V to 2.7 V	7		20	Ω				
r <sub>OL</sub>	Output low	I <sub>OL</sub> = 20 mA	2.3 V to 2.7 V	7		20	Ω				
C <sub>i</sub>	Data inputs	V <sub>I</sub> = V <sub>REF</sub> ± 310 mV	2.5 V			3	3.75	4.25			
	CLK, $\overline{\text{CLK}}$	V <sub>ICR</sub> = 1.25 V, V <sub>I(PP)</sub> = 360mV							3	3.5	4
	$\overline{\text{RESET}}$	V <sub>I</sub> = V <sub>CC</sub> or GND									

† All typical values are at V<sub>CC</sub> = 2.5 V, T<sub>A</sub> = 25°C.



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**timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)**

			$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		UNIT
			MIN	MAX	
$f_{\text{clock}}$	Clock frequency		200		MHz
$t_w$	Pulse duration, CLK, $\overline{\text{CLK}}$ high or low		2.5		ns
$t_{\text{act}}$	Differential inputs active time (see Note 5)		22		ns
$t_{\text{inact}}$	Differential inputs inactive time (see Note 6)		22		ns
$t_{\text{su}}$	Setup time	Fast slew rate (see Notes 7 and 9)	Data before CLK $\uparrow$ , $\overline{\text{CLK}}\downarrow$	0.75	ns
		Slow slew rate (see Notes 8 and 9)		0.9	
$t_h$	Hold time	Fast slew rate (see Notes 7 and 9)	Data after CLK $\uparrow$ , $\overline{\text{CLK}}\downarrow$	0.75	ns
		Slow slew rate (see Notes 8 and 9)		0.9	

- NOTES: 5.  $V_{\text{REF}}$  must be held at a valid input level, and data inputs must be held low for a minimum time of  $t_{\text{act}}$  max, after  $\overline{\text{RESET}}$  is taken high.  
6.  $V_{\text{REF}}$ , data, and clock inputs must be held at valid voltage levels (not floating) for a minimum time of  $t_{\text{inact}}$  max, after  $\overline{\text{RESET}}$  is taken low.  
7. Data signal input slew rate  $\geq 1\text{ V/ns}$   
8. Data signal input slew rate  $\geq 0.5\text{ V/ns}$  and  $< 1\text{ V/ns}$   
9. CLK,  $\overline{\text{CLK}}$  input slew rates are  $\geq 1\text{ V/ns}$ .

**switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)**

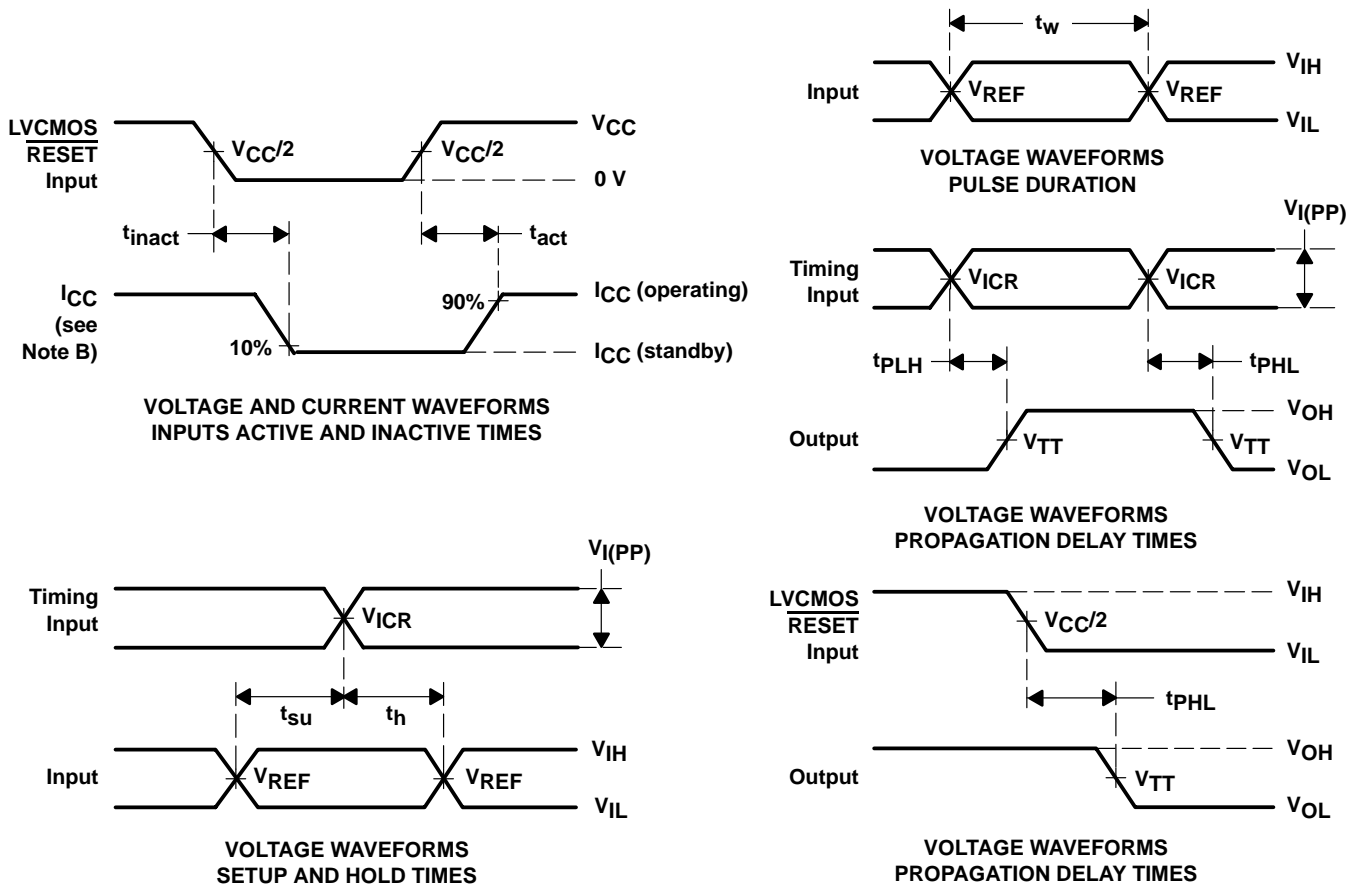
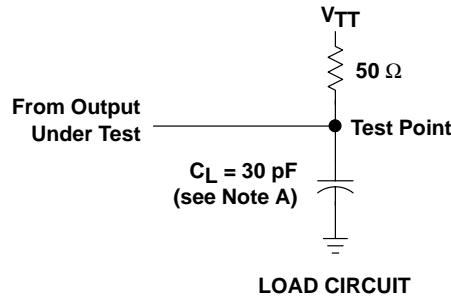
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		UNIT
			MIN	MAX	
$f_{\text{max}}$			200		MHz
$t_{\text{pd}}$	CLK and $\overline{\text{CLK}}$	Q	1.1	3.1	ns
$t_{\text{PHL}}$	$\overline{\text{RESET}}$	Q		5	ns



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**PARAMETER MEASUREMENT INFORMATION**



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B.  $I_{CC}$  tested with clock and data inputs held at  $V_{CC}$  or GND, and  $I_O = 0$  mA.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ , input slew rate =  $1$  V/ns  $\pm 20\%$  (unless otherwise noted).
  - D. The outputs are measured one at a time with one transition per measurement.
  - E.  $V_{TT} = V_{REF} = V_{DDQ}/2$
  - F.  $V_{IH} = V_{REF} + 310$  mV (ac voltage levels) for differential inputs.  $V_{IH} = V_{CC}$  for LVC MOS input.
  - G.  $V_{IL} = V_{REF} - 310$  mV (ac voltage levels) for differential inputs.  $V_{IL} = \text{GND}$  for LVC MOS input.
  - H.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74SSTV32852GKFR	ACTIVE	LFBGA	GKF	114	1000	TBD	SNPB	Level-3-220C-168 HR
SN74SSTV32852ZKFR	ACTIVE	LFBGA	ZKF	114	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF SN74SSTV32852 :**

- Enhanced Product: [SN74SSTV32852-EP](#)

NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74SSTV32852GKFR	LFBGA	GKF	114	1000	330.0	24.4	5.8	16.3	1.8	8.0	24.0	Q1
SN74SSTV32852ZKFR	LFBGA	ZKF	114	1000	330.0	24.4	5.8	16.3	1.8	8.0	24.0	Q1



**TAPE AND REEL BOX DIMENSIONS**

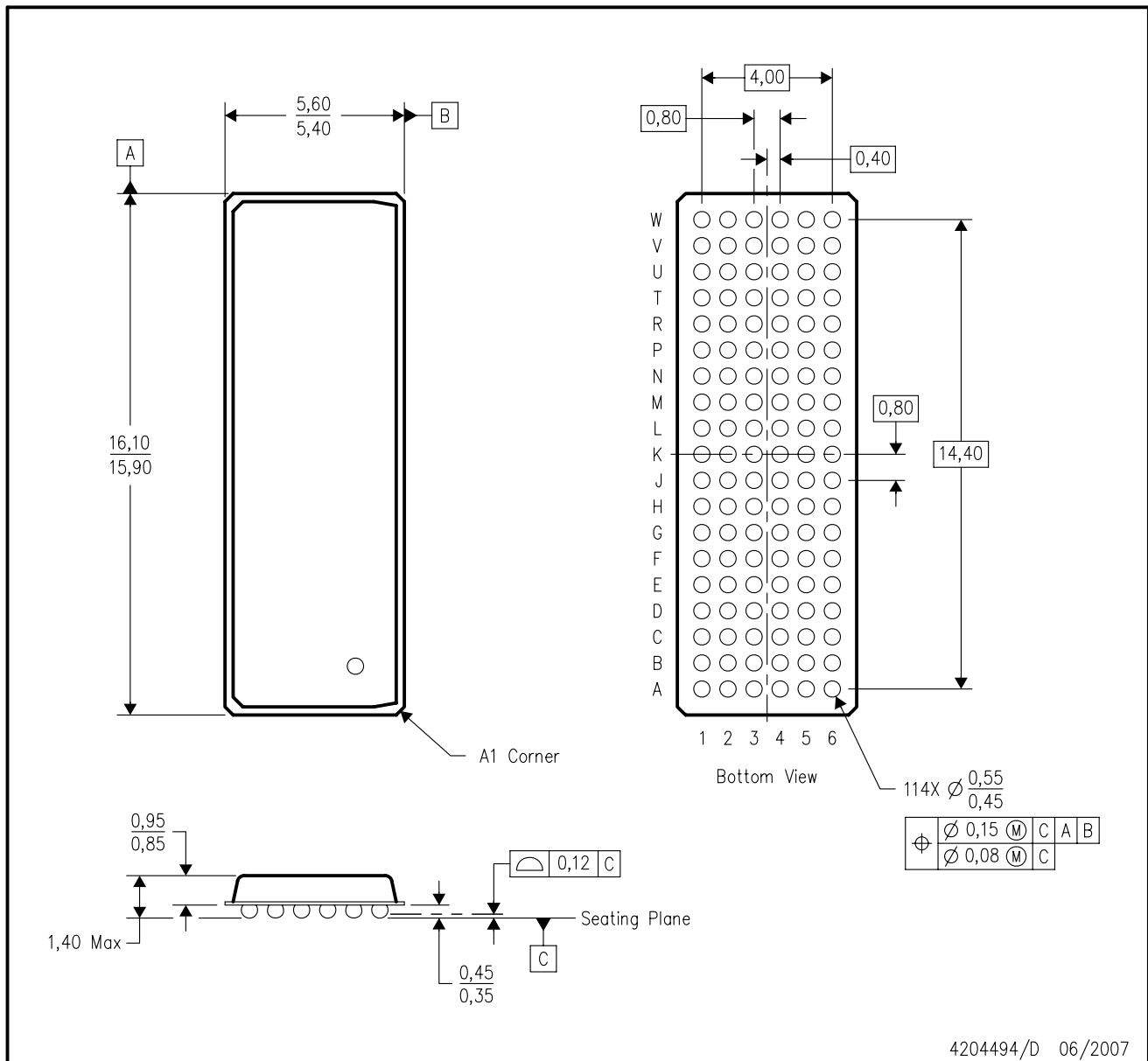


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74SSTV32852GKFR	LFBGA	GKF	114	1000	346.0	346.0	41.0
SN74SSTV32852ZKFR	LFBGA	ZKF	114	1000	346.0	346.0	41.0

ZKF (R-PBGA-N114)

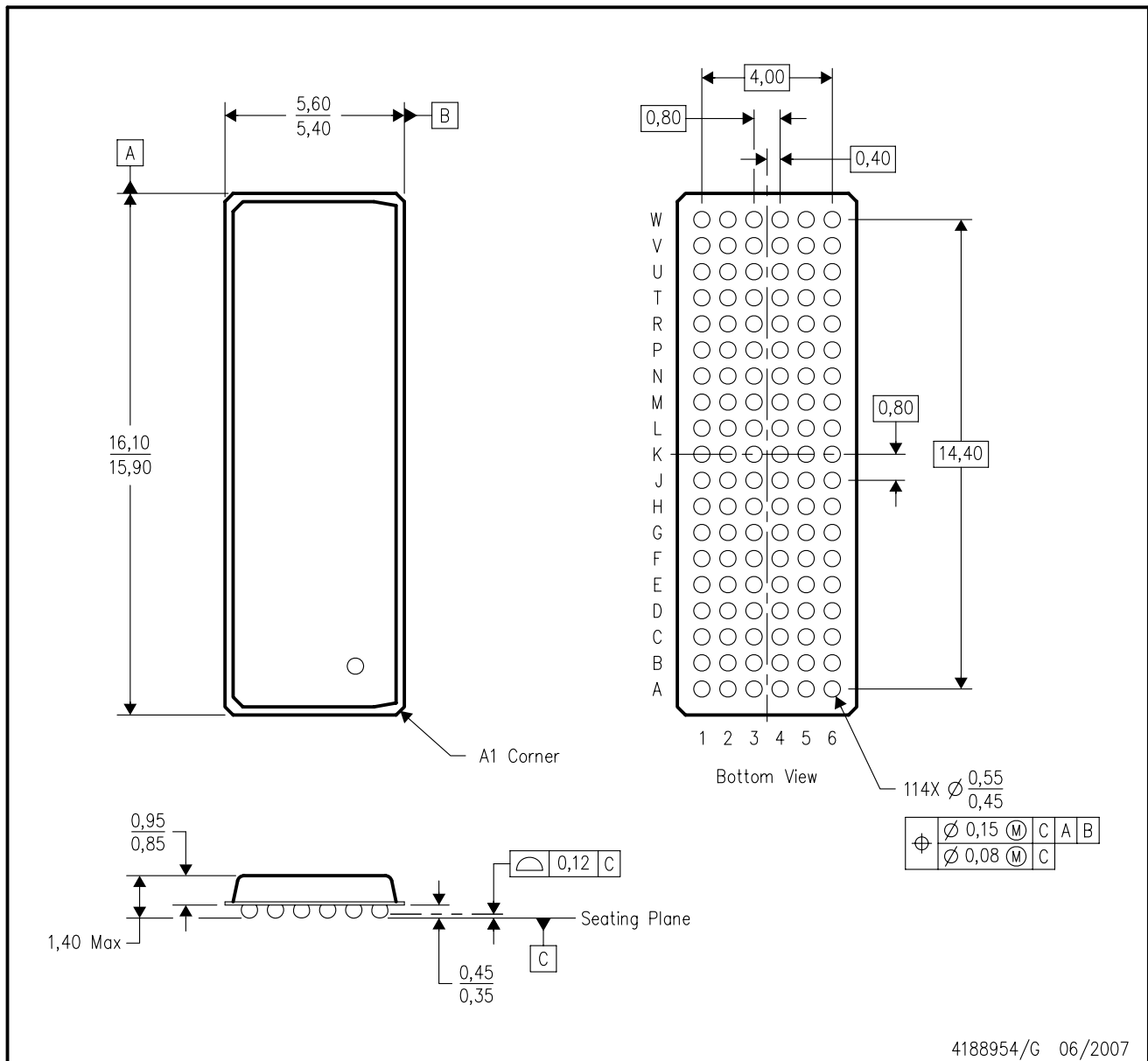
PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-205 variation DC.
  - D. This package is lead-free. Refer to the 114 GKF package (drawing 4188954) for tin-lead (SnPb).

GKF (R-PBGA-N114)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-205 variation DC.
  - D. This package is tin-lead (SnPb). Refer to the 114 ZKF package (drawing 4204494) for lead-free.

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RF/IF and ZigBee® Solutions	<a href="http://www.ti.com/lprf">www.ti.com/lprf</a>

### Applications

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Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
Optical Networking	<a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a>
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